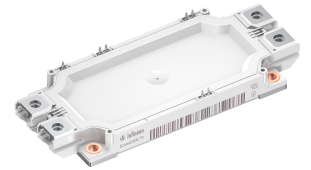


Final datasheet

EconoDUAL™3 module with Trench/Fieldstop IGBT4 and emitter controlled 4 diode and PressFIT / NTC

Features

- Electrical features
 - $V_{CES} = 1200\text{ V}$
 - $I_{C\text{ nom}} = 600\text{ A} / I_{CRM} = 1200\text{ A}$
 - Low $V_{CE,sat}$
 - $T_{vj,op} = 150^{\circ}\text{C}$
 - $V_{CE,sat}$ with positive temperature coefficient
- Mechanical features
 - High power density
 - Isolated base plate
 - PressFIT contact technology
 - Standard housing



Potential applications

- High-power converters
- Motor drives
- Servo drives
- UPS systems
- Wind turbines

Product validation

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

Description

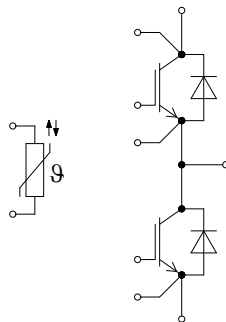


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1 Package

Table 1 Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, $f = 50$ Hz, $t = 1$ min	2.5	kV
Isolation test voltage NTC	$V_{ISOL(NTC)}$	RMS, $f = 50$ Hz, $t = 1$ min	2.5	kV
Material of module baseplate			Cu	
Internal isolation		basic insulation (class 1, IEC 61140)	Al_2O_3	
Creepage distance	$d_{Creep\ nom}$	terminal to baseplate, nom., (PD2, IEC 60664-1, Ed. 3.0)	> 15	mm
Creepage distance	$d_{Creep\ min}$	terminal to baseplate, min., (PD2, IEC 60664-1, Ed. 3.0)	14.7	mm
Creepage distance	$d_{Creep\ nom}$	terminal to terminal, nom., (PD2, IEC 60664-1, Ed. 3.0)	12.1	mm
Creepage distance	$d_{Creep\ min}$	terminal to terminal, min., (PD2, IEC 60664-1, Ed. 3.0)	11.5	mm
Clearance	$d_{Clear\ nom}$	terminal to baseplate, nom.	> 12.5	mm
Clearance	$d_{Clear\ min}$	terminal to baseplate, min.	12.5	mm
Clearance	$d_{Clear\ nom}$	terminal to terminal, nom.	10.0	mm
Clearance	$d_{Clear\ min}$	terminal to terminal, min.	9.6	mm
Comparative tracking index	CTI		> 200	
Relative thermal index (electrical)	RTI	housing	140	°C

Table 2 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Stray inductance module	L_{sCE}			20		nH
Module lead resistance, terminals - chip	$R_{CC'+EE'}$	$T_C = 25$ °C, per switch		1		mΩ
Storage temperature	T_{stg}		-40		125	°C
Mounting torque for module mounting	M	- Mounting according to valid application note	M5, Screw	3	6	Nm
Terminal connection torque	M	- Mounting according to valid application note	M6, Screw	3	6	Nm
Weight	G			345		g

2 IGBT, Inverter

Table 3 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Collector-emitter voltage	V_{CES}	$T_{vj} = 25\text{ °C}$	1200	V
Continuous DC collector current	I_{CDC}	$T_{vj\text{ max}} = 175\text{ °C}$ $T_C = 100\text{ °C}$	600	A
Repetitive peak collector current	I_{CRM}	t_p limited by $T_{vj\text{ op}}$	1200	A
Gate-emitter peak voltage	V_{GES}		± 20	V

Table 4 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Collector-emitter saturation voltage	$V_{CE\text{ sat}}$	$I_C = 600\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25\text{ °C}$	1.75	2.10	V
			$T_{vj} = 125\text{ °C}$	2.00		
			$T_{vj} = 150\text{ °C}$	2.05		
Gate threshold voltage	V_{GETh}	$I_C = 13\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25\text{ °C}$	5.20	5.80	6.40	V
Gate charge	Q_G	$V_{GE} = \pm 15\text{ V}$		4.4		μC
Internal gate resistor	R_{Gint}	$T_{vj} = 25\text{ °C}$		1.2		Ω
Input capacitance	C_{ies}	$f = 1000\text{ kHz}, T_{vj} = 25\text{ °C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		37		nF
Reverse transfer capacitance	C_{res}	$f = 1000\text{ kHz}, T_{vj} = 25\text{ °C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		2.05		nF
Collector-emitter cut-off current	I_{CES}	$V_{CE} = 1200\text{ V}, V_{GE} = 0\text{ V}$ $T_{vj} = 25\text{ °C}$			3	mA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25\text{ °C}$			400	nA
Turn-on delay time (inductive load)	t_{don}	$I_C = 600\text{ A}, V_{CC} = 600\text{ V}, V_{GE} = \pm 15\text{ V}, R_{Gon} = 0.51\text{ }\Omega$	$T_{vj} = 25\text{ °C}$	0.180		μs
			$T_{vj} = 125\text{ °C}$	0.220		
			$T_{vj} = 150\text{ °C}$	0.220		
Rise time (inductive load)	t_r	$I_C = 600\text{ A}, V_{CC} = 600\text{ V}, V_{GE} = \pm 15\text{ V}, R_{Gon} = 0.51\text{ }\Omega$	$T_{vj} = 25\text{ °C}$	0.070		μs
			$T_{vj} = 125\text{ °C}$	0.080		
			$T_{vj} = 150\text{ °C}$	0.080		
Turn-off delay time (inductive load)	t_{doff}	$I_C = 600\text{ A}, V_{CC} = 600\text{ V}, V_{GE} = \pm 15\text{ V}, R_{Goff} = 0.51\text{ }\Omega$	$T_{vj} = 25\text{ °C}$	0.450		μs
			$T_{vj} = 125\text{ °C}$	0.550		
			$T_{vj} = 150\text{ °C}$	0.590		

(table continues...)

Table 4 (continued) **Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Fall time (inductive load)	t_f	$I_C = 600\text{ A}, V_{CC} = 600\text{ V},$ $V_{GE} = \pm 15\text{ V}, R_{Goff} = 0.51\ \Omega$	$T_{vj} = 25\text{ °C}$	0.070		μs
			$T_{vj} = 125\text{ °C}$	0.110		
			$T_{vj} = 150\text{ °C}$	0.120		
Turn-on energy loss per pulse	E_{on}	$I_C = 600\text{ A}, V_{CC} = 600\text{ V},$ $L_\sigma = 35\text{ nH}, V_{GE} = \pm 15\text{ V},$ $R_{Gon} = 0.51\ \Omega, di/dt =$ $7000\text{ A}/\mu\text{s} (T_{vj} = 150\text{ °C})$	$T_{vj} = 25\text{ °C}$	29		mJ
			$T_{vj} = 125\text{ °C}$	47		
			$T_{vj} = 150\text{ °C}$	53.5		
Turn-off energy loss per pulse	E_{off}	$I_C = 600\text{ A}, V_{CC} = 600\text{ V},$ $L_\sigma = 35\text{ nH}, V_{GE} = \pm 15\text{ V},$ $R_{Goff} = 0.51\ \Omega, dv/dt =$ $3100\text{ V}/\mu\text{s} (T_{vj} = 150\text{ °C})$	$T_{vj} = 25\text{ °C}$	55		mJ
			$T_{vj} = 125\text{ °C}$	81.5		
			$T_{vj} = 150\text{ °C}$	90		
SC data	I_{SC}	$V_{GE} \leq 15\text{ V}, V_{CC} = 800\text{ V},$ $V_{CEmax} = V_{CES} - L_{sCE} \cdot di/dt$	$t_p \leq 10\ \mu\text{s},$ $T_{vj} = 150\text{ °C}$	2700		A
Thermal resistance, junction to case	R_{thJC}	per IGBT			0.0370	K/W
Thermal resistance, case to heat sink	R_{thCH}	per IGBT, $\lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$		0.0350		K/W
Temperature under switching conditions	$T_{vj\ op}$		-40		150	°C

3 Diode, Inverter

Table 5 **Maximum rated values**

Parameter	Symbol	Note or test condition	Values	Unit	
Repetitive peak reverse voltage	V_{RRM}	$T_{vj} = 25\text{ °C}$	1200	V	
Continuous DC forward current	I_F		600	A	
Repetitive peak forward current	I_{FRM}	$t_p = 1\text{ ms}$	1200	A	
I^2t - value	I^2t	$t_p = 10\text{ ms}, V_R = 0\text{ V}$	$T_{vj} = 125\text{ °C}$	35000	A ² s
			$T_{vj} = 150\text{ °C}$	33000	

Table 6 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Forward voltage	V_F	$I_F = 600 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$		1.90	2.30	V
			$T_{vj} = 125 \text{ °C}$		1.85		
			$T_{vj} = 150 \text{ °C}$		1.80		
Peak reverse recovery current	I_{RM}	$V_{CC} = 600 \text{ V}, I_F = 600 \text{ A}, V_{GE} = -15 \text{ V}, -di_F/dt = 7000 \text{ A}/\mu\text{s} (T_{vj} = 150 \text{ °C})$	$T_{vj} = 25 \text{ °C}$		385		A
			$T_{vj} = 125 \text{ °C}$		490		
			$T_{vj} = 150 \text{ °C}$		520		
Recovered charge	Q_r	$V_{CC} = 600 \text{ V}, I_F = 600 \text{ A}, V_{GE} = -15 \text{ V}, -di_F/dt = 7000 \text{ A}/\mu\text{s} (T_{vj} = 150 \text{ °C})$	$T_{vj} = 25 \text{ °C}$		55.5		μC
			$T_{vj} = 125 \text{ °C}$		110		
			$T_{vj} = 150 \text{ °C}$		125		
Reverse recovery energy	E_{rec}	$V_{CC} = 600 \text{ V}, I_F = 600 \text{ A}, V_{GE} = -15 \text{ V}, -di_F/dt = 7000 \text{ A}/\mu\text{s} (T_{vj} = 150 \text{ °C})$	$T_{vj} = 25 \text{ °C}$		28		mJ
			$T_{vj} = 125 \text{ °C}$		50.5		
			$T_{vj} = 150 \text{ °C}$		60		
Thermal resistance, junction to case	R_{thJC}	per diode			0.0710	K/W	
Thermal resistance, case to heat sink	R_{thCH}	per diode, $\lambda_{grease} = 1 \text{ W}/(\text{m}\cdot\text{K})$		0.0395		K/W	
Temperature under switching conditions	$T_{vj\text{op}}$		-40		150	°C	

4 NTC-Thermistor

Table 7 Characteristic values

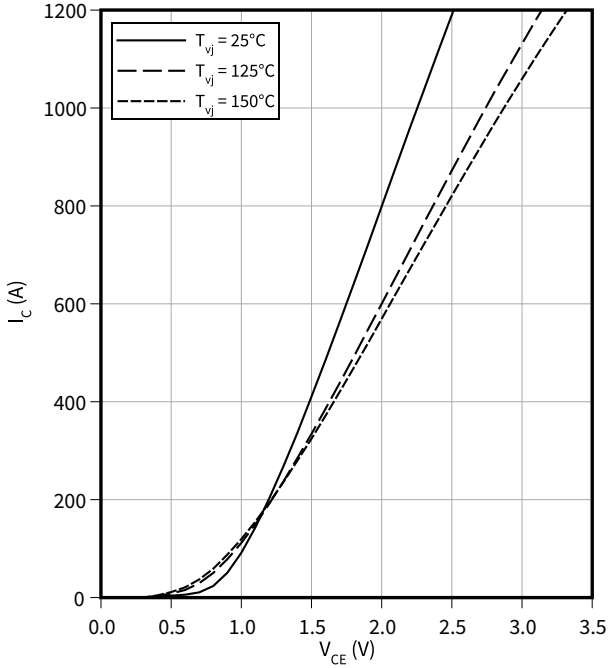
Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rated resistance	R_{25}	$T_{NTC} = 25 \text{ °C}$		5		k Ω
Deviation of R_{100}	$\Delta R/R$	$T_{NTC} = 100 \text{ °C}, R_{100} = 493 \text{ }\Omega$	-5		5	%
Power dissipation	P_{25}	$T_{NTC} = 25 \text{ °C}$			20	mW
B-value	$B_{25/50}$	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$		3375		K
B-value	$B_{25/80}$	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$		3411		K
B-value	$B_{25/100}$	$R_2 = R_{25} \exp[B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$		3433		K

Note: For an analytical description of the NTC characteristics please refer to AN2009-10, chapter 4.

5 Characteristics diagrams

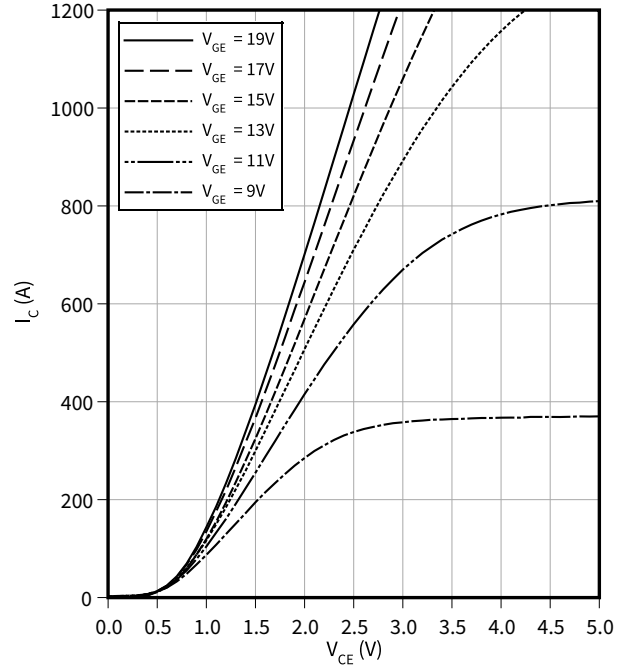
Output characteristic (typical), IGBT, Inverter

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



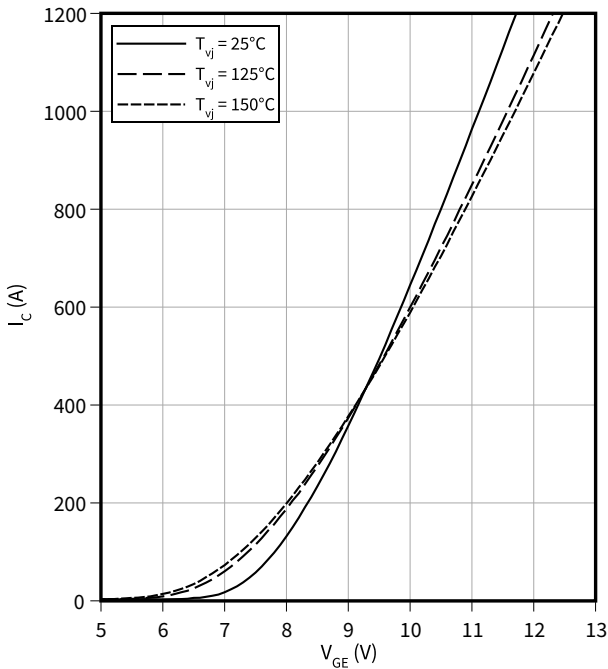
Output characteristic field (typical), IGBT, Inverter

$I_C = f(V_{CE})$
 $T_{vj} = 150\text{ °C}$



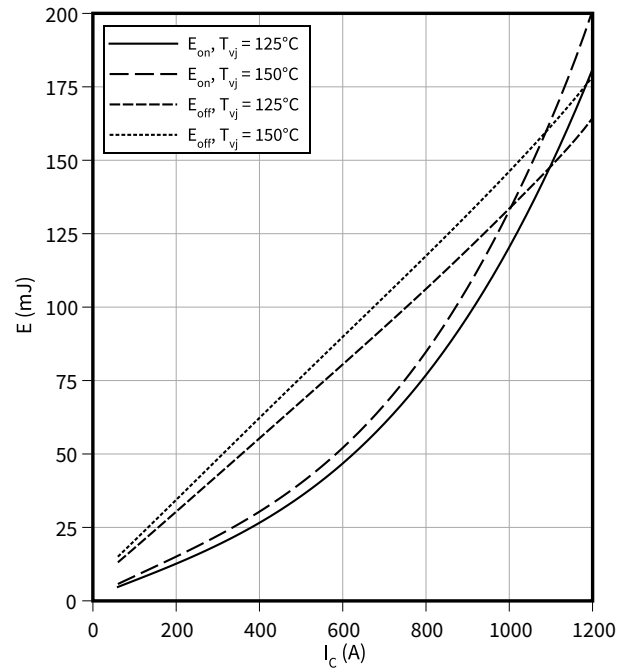
Transfer characteristic (typical), IGBT, Inverter

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



Switching losses (typical), IGBT, Inverter

$E = f(I_C)$
 $R_{Goff} = 0.51\ \Omega, R_{Gon} = 0.51\ \Omega, V_{GE} = \pm 15\text{ V}, V_{CC} = 600\text{ V}$

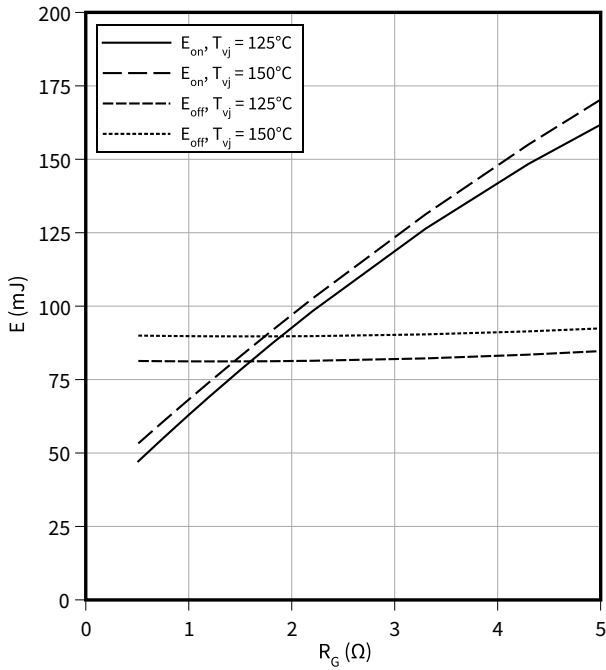


5 Characteristics diagrams

Switching losses (typical), IGBT, Inverter

$E = f(R_G)$

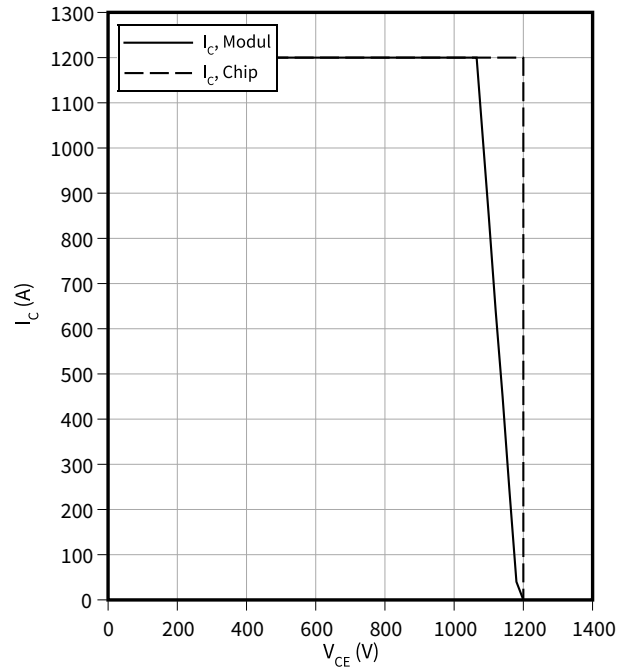
$V_{GE} = \pm 15 \text{ V}, I_C = 600 \text{ A}, V_{CC} = 600 \text{ V}$



Reverse bias safe operating area (RBSOA), IGBT, Inverter

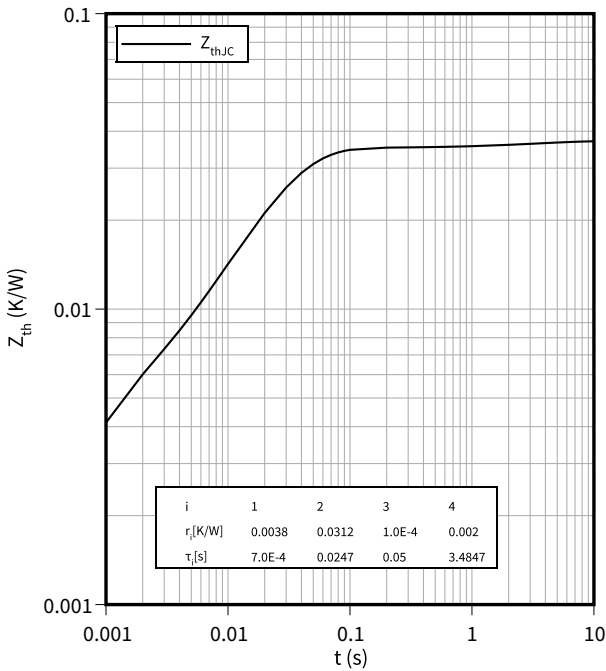
$I_C = f(V_{CE})$

$R_{Goff} = 0.51 \Omega, V_{GE} = \pm 15 \text{ V}, T_{vj} = 150 \text{ °C}$



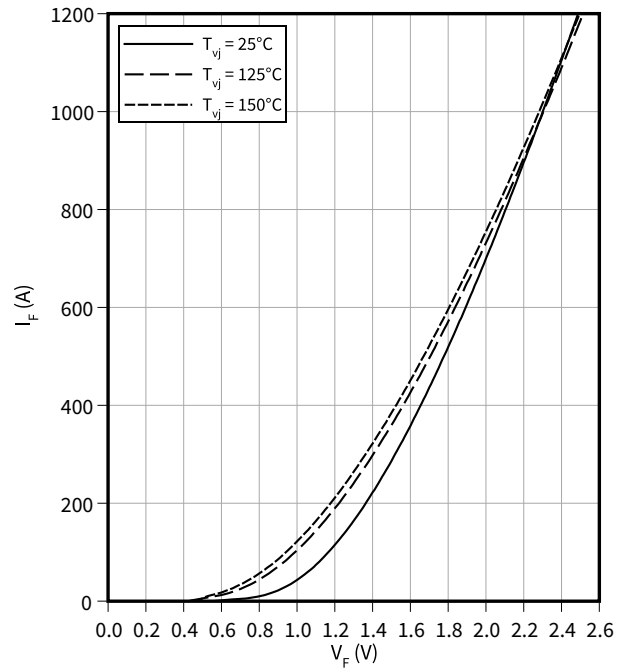
Transient thermal impedance, IGBT, Inverter

$Z_{th} = f(t)$



Forward characteristic (typical), Diode, Inverter

$I_F = f(V_F)$

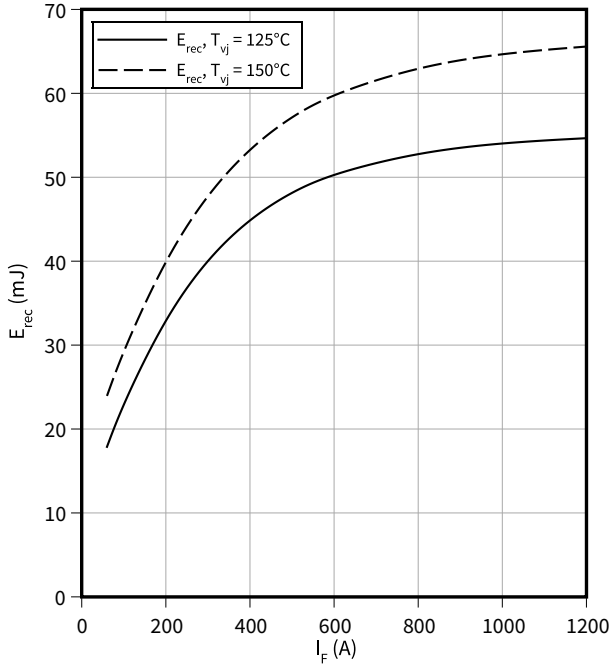


5 Characteristics diagrams

Switching losses (typical), Diode, Inverter

$E_{rec} = f(I_F)$

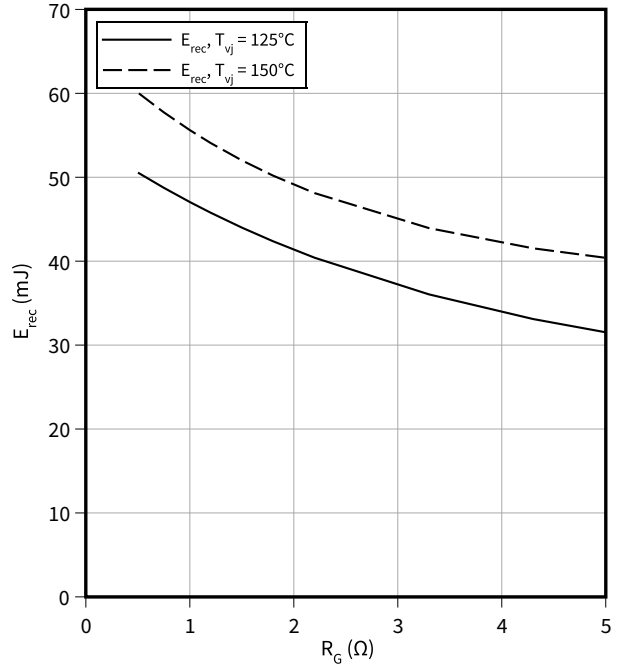
$R_{Gon} = 0.51 \Omega, V_{CC} = 600 V$



Switching losses (typical), Diode, Inverter

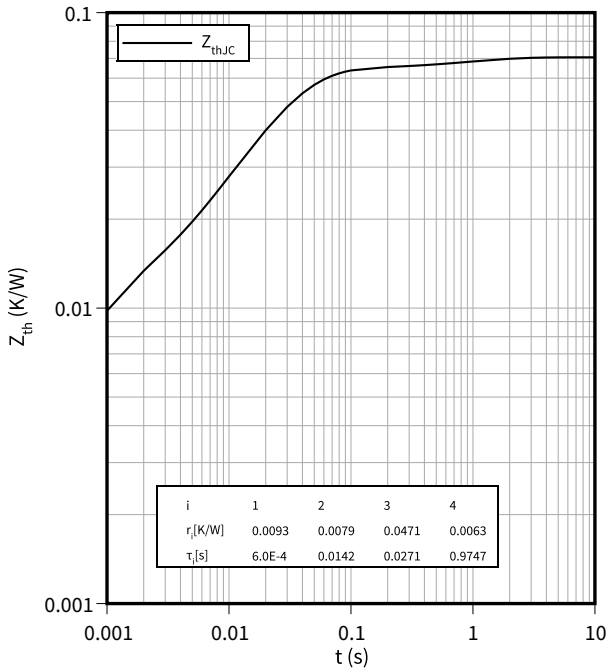
$E_{rec} = f(R_G)$

$I_F = 600 A, V_{CC} = 600 V$



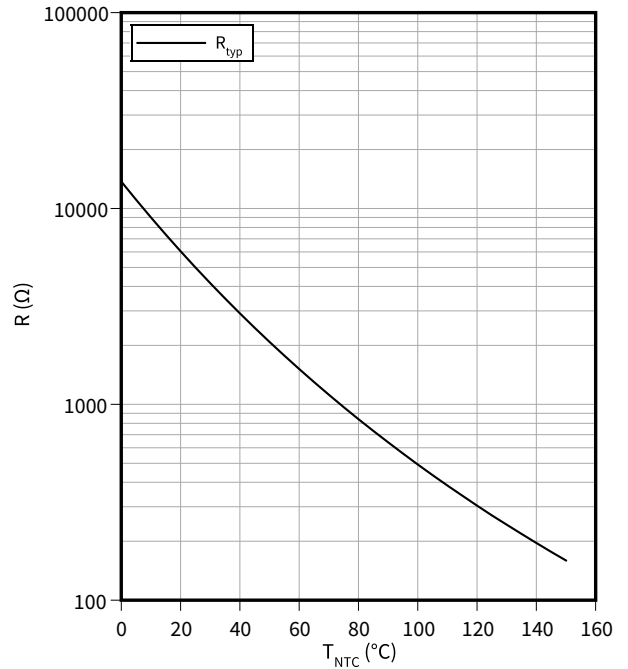
Transient thermal impedance, Diode, Inverter

$Z_{th} = f(t)$



Temperature characteristic (typical), NTC-Thermistor

$R = f(T_{NTC})$



6 Circuit diagram

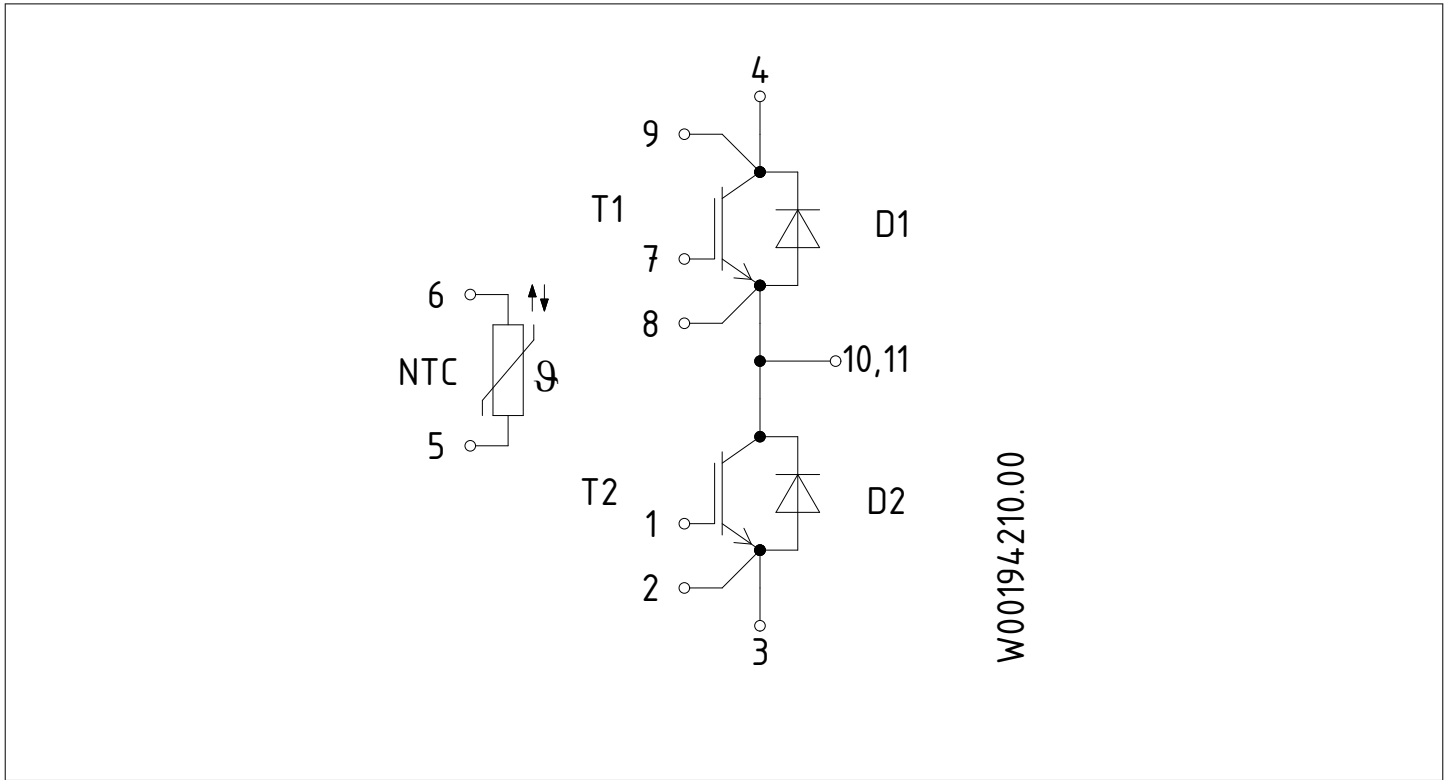


Figure 1

7 Package outlines

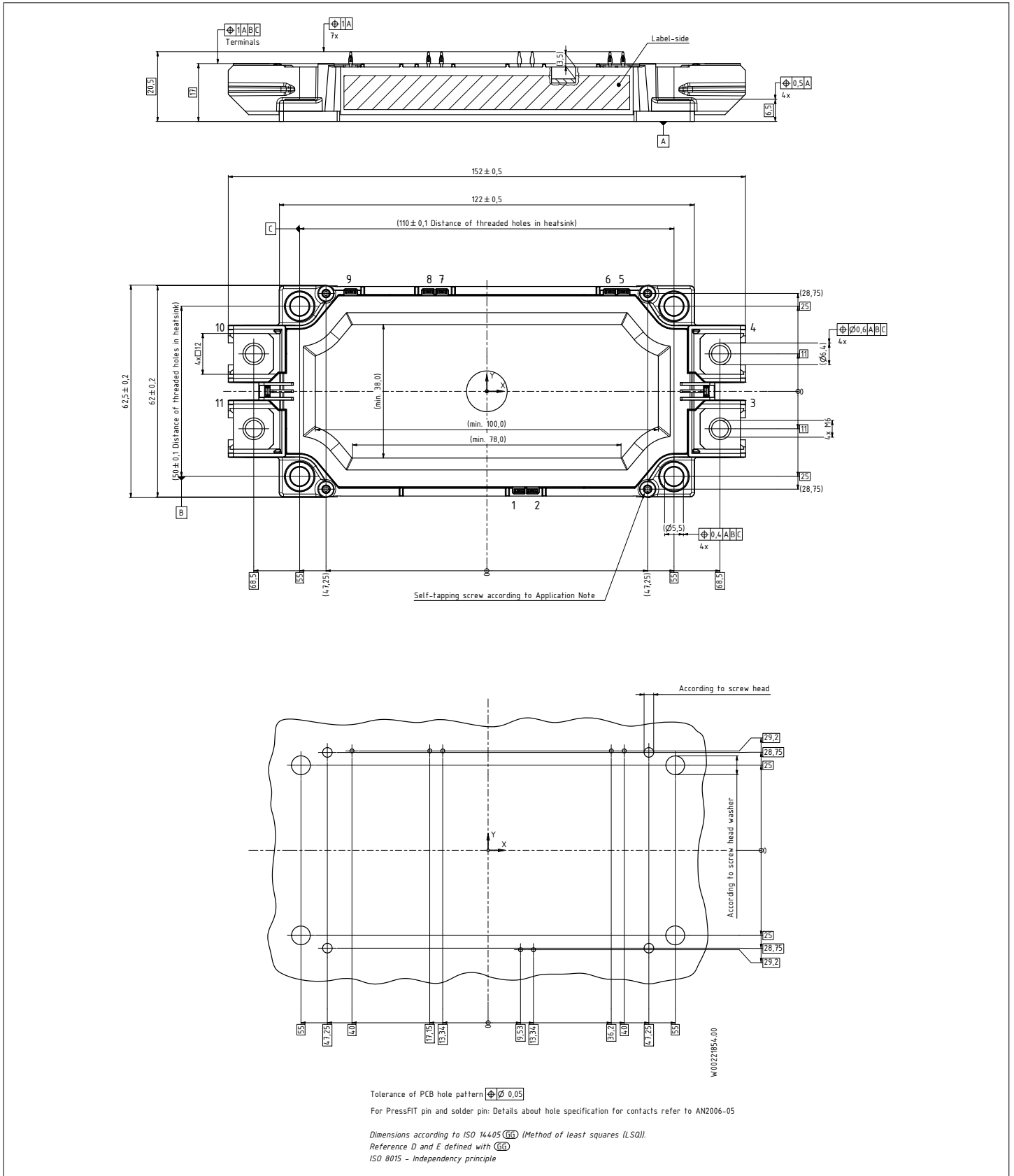


Figure 2

8 Module label code


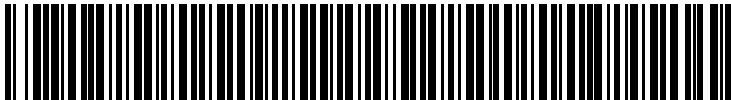
Module label code			
Code format	Data Matrix	Barcode Code128	
Encoding	ASCII text	Code Set A	
Symbol size	16x16	23 digits	
Standard	IEC24720 and IEC16022	IEC8859-1	
Code content	Content	Digit	Example
	Module serial number	1 - 5	71549
	Module material number	6 - 11	142846
	Production order number	12 - 19	55054991
	Date code (production year)	20 - 21	15
	Date code (production week)	22 - 23	30
Example	 		
	71549142846550549911530		71549142846550549911530

Figure 3

Revision history

Document revision	Date of release	Description of changes
V1.0	2013-04-03	Target datasheet
V1.1	2013-08-05	Target datasheet
V3.0	2013-11-05	Final datasheet
n/a	2020-09-01	Datasheet migrated to a new system with a new layout and new revision number schema: target or preliminary datasheet = 0.xy; final datasheet = 1.xy
1.10	2024-03-15	Final datasheet

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